



PFR™-800 AUS™ SR2

PKG 用現像型ソルダーレジストドライフィルム

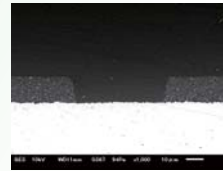
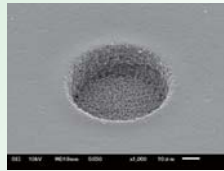
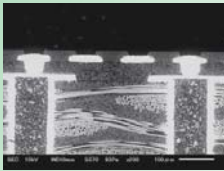
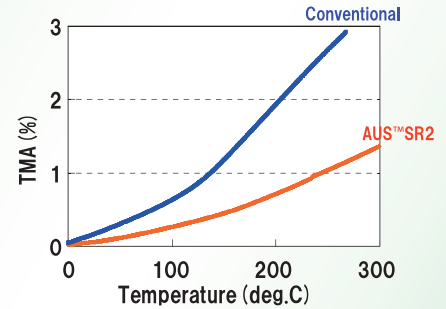
Dry Film Solder Resist for PKG Substrate Application **PHOTOFINER™**

特長 Features

- 高 Tg / 低 CTE (alpha 1=20ppm-25ppm)
- 優れた解像性
- 優れた電気特性

特性 Properties

ガラス転移点 Tg *TMA method	145-155 °C
線膨張係数 CTE (alpha 1)	20-25 ppm
弾性率 Young's modulus	4.5-5.0 GPa
破壊強度 Tensile strength	60-70 MPa
破壊伸び率 Elongation	2.0-2.5 %



SRO 50μm, thickness 20μm

PFR™-800 AUS™ SR1 PKG 用現像型ソルダーレジストドライフィルム

Dry Film Solder Resist for PKG Substrate Application

PSR™-4000 AUS™ G2 PKG 用現像型液状ソルダーレジスト

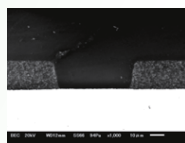
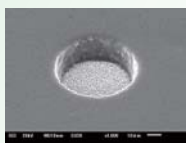
Liquid Solder Resist for PKG Substrate Application

特長 Features

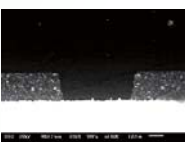
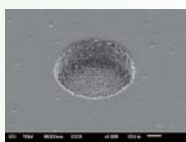
- 投影機 / DI 露光機対応
- 高精細での優れた電気特性
- 優れた塗膜物性
- 徹底した粗粒管理

特性 Properties

	AUS™ SR1	AUS™ G2
ガラス転移点 Tg *TMA method	130-140 °C	135-145 °C
線膨張係数 CTE (alpha 1)	40-45 ppm	40-45 ppm
弾性率 Young's modulus	3.5-4.5 GPa	4.0-4.5 GPa
破壊強度 Tensile strength	70-75 MPa	80-85 MPa
破壊伸び率 Elongation	3.5-4.0 %	3.0-3.5 %



AUS™ SR1 SRO 50μm, thickness 20μm



AUS™ G2 SRO 50μm, thickness 20μm

Weibull Plot in BHAST L/S=15/10μm, 130°C, 85%, 12V

